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SERIALIZED		FILED		MAILED	
JULY 1998		JULY 1998		JULY 1998	
U.S. UTILITY Patent Application					
O.P.E.		PATENT DATE		EXAMINER	
SCANNED		R 2 AA		D. NGUYEN	
APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/687048	F	257	6667	25714	D. NGUYEN
APPLICANTS	Tae Lee Young Chung Mu Seo				
TITLE	Leadframe and semiconductor package with improved solder joint strength				
PTO-8990 12-98					

ISSUING CLASSIFICATION

TERMINAL DISCLAIMER		DRAWINGS		CLAIMS ALLOWED	
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.		Sheets Drwg. _____ Figs. Drwg. _____ Print Fig. _____		Total Claims _____ Print Claim for D.O. _____	
NOTICE OF ALLOWANCE MAILED					
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____		(Assistant Examiner) _____ (Date) _____		(Primary Examiner) _____ (Date) _____	
ISSUE FEE					
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ISSUE BATCH NUMBER					

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